

# Performance Evaluation of a Self-Biased Current Reference Source Using Uniformly Doped and Halo-Implanted Channel Transistors

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**Abstract**—This paper presents a performance comparison of a self-biased current reference source tolerant to supply voltage variations built with uniformly doped and halo-implanted channel transistors. The proposed topology was designed in a 130 nm CMOS process to provide a current reference of 30  $\mu\text{A}$  under 3.3 V supply voltage. The results obtained proves a better performance of the uniformly doped transistors with a current reference's sensitivity to supply voltage of 0.7% and a temperature coefficient of 23.8 ppm/ $^{\circ}\text{C}$ , whilst the halo-implanted transistors has a current reference's sensitivity to supply voltage of 15.3% and a temperature coefficient of 66.8 ppm/ $^{\circ}\text{C}$ .

**Index Terms**—current source, CMOS current reference source, halo-implanted CMOS transistor.

## I. INTRODUCTION

A current reference source is a fundamental building block in an integrated circuit design and must be able to supply an accurate current with a reduced current sensitivity with respect to temperature and voltage supply. Usually, a current reference source is load dependent, but it is possible to avoid this effect adding circuits that isolate the current reference from the load and maintain your performance [1].

In the design of current reference sources, there is an effort to make the current reference value independent from the supply voltage [2, 3]. A way to minimize the dependence of the current reference in relation to the supply voltage is to implement a circuit that the operating point is established by the current reference itself. This concept can be illustrated when a positive feedback loop requires the input current to be equal to the output current, characterizing a self-biased current reference source [4].

The uniformly doped transistors are the most advisable for analog operations. However, in this paper we introduce an implementation of the current reference using halo-implanted, used in digital circuit designs [5]. Due to doping variation along the channel, the halo-implanted have a fluctuation in the mobility of the carriers and in the threshold voltage, resulting in a low output impedance and a high mismatch [6]–[8].

In this paper, we introduce a self-biased current source using a 130 nm CMOS technology with a 3.3 V supply voltage and a 30  $\mu\text{A}$  current. Furthermore, the objective of this work is compare the performance of the self-biased current

using transistors with uniformly doped and halo-implanted channels. The results obtained shows a better performance of the uniformly doped transistors for having a current reference's sensitivity to supply voltage and a temperature coefficient lower than the halo-implanted transistors.

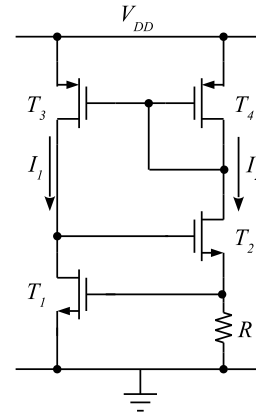


Fig. 1. Self-biased current reference source circuit.

The paper has the following structure. In Section II, grounds the self-biased current source threshold voltage based. In Section III, describes the circuit topology design. In Section IV the results obtained in the implementation of the circuit are discussed. Finally, in Section V, presents the conclusions and final considerations of this paper.

## II. A SELF-BIASED CURRENT REFERENCE SOURCE BASED ON THE MOSFET THRESHOLD VOLTAGE

The circuit seen in Fig. 1 was based on the concept of positive feedback loop and represents a self-biased current source. The current source block consists on matched  $T_1$  and  $T_2$  MOS transistors and a resistor  $R$  that dictates the value of  $I_2$ , as

$$I_2 = \frac{V_{GS1}}{R}, \quad (1)$$

which depends weakly on  $I_1$ , given by

$$I_1 = \mu_n C_{ox} \left( \frac{W}{L} \right)_1 (V_{GS1} - V_{TH})^2, \quad (2)$$

neglecting the body effect [1].

Manipulating (1) and (2) it can be derived expressions to  $V_{GS1}$  and  $I_2$  as

$$V_{GS1} = \sqrt{\frac{2I_1L}{\mu_n C_{ox} W}} + V_{TH1} \text{ and} \quad (3)$$

$$I_2 = \frac{\sqrt{\frac{2I_1L}{\mu_n C_{ox} W}}}{R} + \frac{V_{TH1}}{R}. \quad (4)$$

Transistors  $T_3$  and  $T_4$  of Fig. 1 are configured as a current mirror thus  $I_2$  is copied to  $I_1$ . Hence,  $I_1$  current flows to  $T_1$  creating a  $V_{GS1}$  voltage determining  $I_2$  current that flows through  $R$ . This relationship implements a positive feedback. Thus, the balance between  $I_1$  and  $I_2$ , determined by  $V_{GS1}$ , causes the circuit to self-biasing [4].

Therefore, equating  $I_1$  and  $I_2$  regarding  $V_{GS1}$ , it is possible to obtain the current reference value  $I_Q$  as

$$I_Q = I_1 = I_2 = \frac{V_{TH1}}{R} + \frac{1}{\beta_1 R^2} + \frac{1}{R} \sqrt{\frac{2V_{TH1}}{\beta_1 R} + \frac{1}{\beta_1^2 R^2}}, \quad (5)$$

where  $\beta_1 = \mu_n C_{ox} (W/L)_1$ .

There are two operating points in which  $I_1$  and  $I_2$  are equal, when  $I_1 = I_2 = 0$  and  $I_1 = I_2 = I_Q$ . When  $I_1 = I_2 = 0$ , the gain around the positive feedback is deliberately made greater than unity, causing  $I_1$  and  $I_2$  to intersect at a point away from the origin. The operating point away from the origin is the value of  $I_Q$  current reference, in which the gain of the positive feedback is small causing  $I_1$  and  $I_2$  stabilizing in the intended  $I_Q$  current reference value [1].

The circuit sensitivity  $S_{V_{DD}}^{I_Q}$  is a relationship between the reference and supply voltage characterizing the performance of the current reference source allowing comparisons, then

$$S_{V_{DD}}^{I_Q} = \frac{V_{DD}}{I_Q} \frac{\partial I_Q}{\partial V_{DD}} \times 100. \quad (6)$$

Despite the absence of a temperature compensation block, another performance indicator for the circuit in Fig. 1 is the variation of the current reference regarding the temperature. According to [4], the temperature coefficient is calculated by deriving the current equation to the temperature. Thus, the temperature coefficient of the circuit in Fig. 1 is

$$TC = \frac{1}{I_Q} \frac{\partial I_Q}{\partial T} = \frac{1}{V_{GS1}} \frac{\partial V_{GS1}}{\partial T} - \frac{1}{R} \frac{\partial R}{\partial T}. \quad (7)$$

### III. DESIGN OF A CURRENT REFERENCE SOURCE IN A 130 NM CMOS PROCESS

The project and simulation were performed using the BSIM4v4 model for an GF 130 nm CMOS process (GF-8RF). All simulations were performed at room temperature (27 °C).

In the simulation of the circuit seen in Fig. 1, a 3.3 V supply voltage was chosen. For a 30  $\mu$ A current flows at a 30 k $\Omega$  resistance, is required a voltage of 0.9 V over  $R$ . Then,  $T_2$  and  $T_4$  has a voltage drop of, approximately, 1.2 V.

The resistor  $R$  was chosen with precision polysilicon, for having the smallest  $TC$  among those available in the GF 130 nm CMOS process, 1.70 ppm/°C, although the purpose of the project is only the independence of the current reference regarding to the power supply variations.

### A. Transistor sizing

A transistor with a long channel is the most suitable for analog operations, as it is possible to neglect the effect of modulating the length of the channel. Therefore, we define that the channel length of the nMOS and pMOS transistors would be respectively  $50L_{min}$  and  $5L_{min}$ , where  $L_{min}$  of the GF 130 nm CMOS process is equal to 500 nm for 3.3 V the uniformly doped transistor. We choose to maintain the same length for the halo-implanted transistor. although the width changes as  $u_n C_{ox}$  and  $V_{TH}$  are different from uniformly doped, then for the same  $I_{DS}$  current, halo-implanted transistors needs to compensate in width. Table I contains the aspect ratios (W/L).

TABLE I  
TRANSISTORS ASPECT RATIO

Transistors [ $\mu\text{m}/\mu\text{m}$ ]	Uniformly Doped	Halo- Implanted
$T_1$ and $T_2$	36.5 / 25.0	5.4 / 25.0
$T_3$ and $T_4$	5.4 / 2.5	2.3 / 2.5

### B. Start-up Circuit

A start-up circuit is used to ensure that the circuit reaches the condition of  $I_1 = I_2 = I_Q$ . Therefore, we implement from Fig. 2a and 2b, in order to compare the start-up time and the active area.

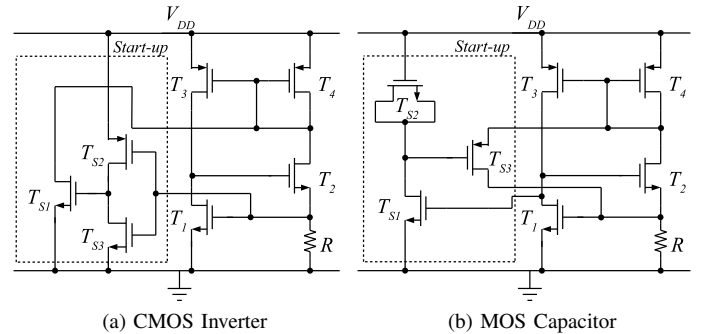


Fig. 2. Self-Biasing Reference Source with a startup circuit.

The start-up circuit in Fig. 2a was based on [4] in which  $T_{S2}$  and  $T_{S3}$  form a CMOS inverter. The circuit in Fig. 2b was based on [9], an approach that does not consume static energy and is more tolerant to supply voltage variation. The circuit uses the  $T_{S2}$  transistor operating as a CMOS capacitor.

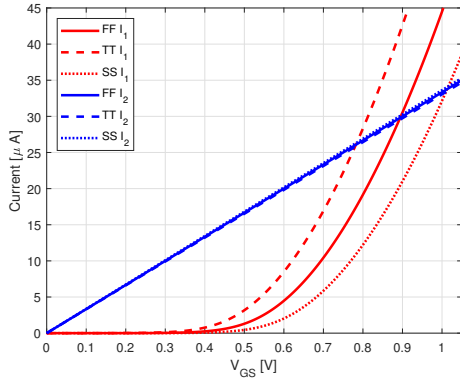
In both start-up circuit design, only halo-implanted transistors with minimal dimensions W/L equals to 160 nm/120 nm were used. The start-up circuit only ensure the reference circuit begins to operate and then stops interfering with the reference circuit operation.

## IV. RESULTS AND DISCUSSION

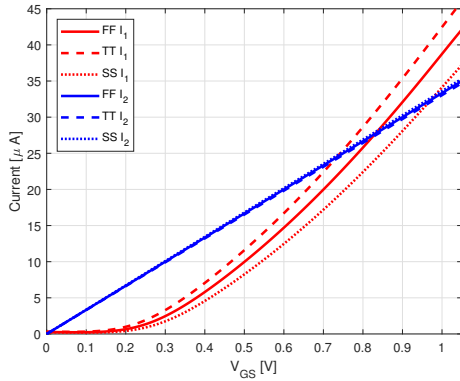
In order to obtain a behavioral estimation of this circuit related to fabrication process variations we perform corners and Monte Carlo simulations. The corners simulation were performed using FF, TT and SS models, i.e., process variations

for fast, typical and slow nMOS and pMOS transistors, respectively. From Fig. 3a,  $I_2$  shows no relevant variation because, as seen in (1), it depends on resistance  $R$  value which is barely affected by the process variation. However, as seen in (2),  $I_1$  depends on  $\beta$  which varies according to the manufacturing process. Thus, the current reference  $I_Q$  stabilizes in different values in FF and SS models. The values of  $I_Q$  found for FF, TT and SS models are, respectively,  $25.8 \mu\text{A}$ ,  $30.0 \mu\text{A}$  and  $34.2 \mu\text{A}$ .

The same corners simulation we perform for the circuit using halo-implanted transistors, the results are shown in Fig. 3b. The same variation impact of  $\beta$  in  $I_1$  and the low variation of  $I_2$  can be observed. In which causes the variation of the current reference  $I_Q$  because they are not able to maintain the intended biasing. The values of  $I_Q$  found for FF, TT and SS models in this circuit are, respectively,  $24.3 \mu\text{A}$ ,  $27.7 \mu\text{A}$  and  $33.0 \mu\text{A}$ .



(a) Uniformly Doped

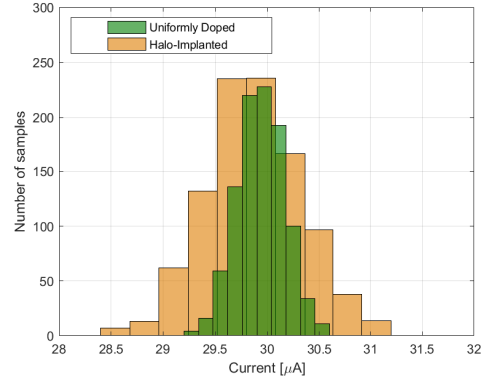
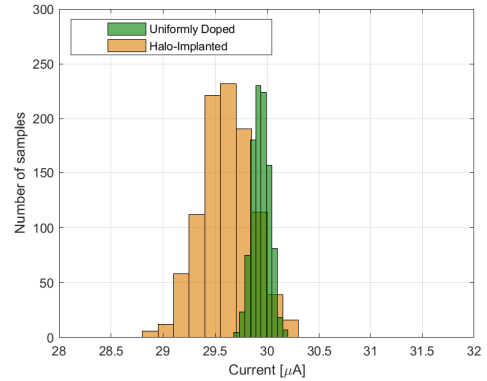


(b) Halo-Implanted

Fig. 3. Behavior of  $I_1$  and  $I_2$  to process corners.

The Monte Carlo simulation analyses the mismatch variations related to  $I_1$  and  $I_2$  using halo-implanted and uniformly doped transistors. Fig. 4 shows the results obtained in histograms of the  $I_1$  and  $I_2$  behavior for uniformly doped and halo-implanted transistors.

Analyzing the results obtained from the Monte Carlo simulation, the high mismatch characteristic of halo-implanted transistors can be noticed, because their standard deviation is higher compared to uniformly doped transistors, as  $0.48\%$  and  $0.23\%$  for the halo-implanted and uniformly doped, re-

(a) Current  $I_1$ (b) Current  $I_2$ Fig. 4. Behavior of  $I_1$  and  $I_2$  in histograms using uniformly doped and halo-implanted transistors in a Monte Carlo simulation analysing mismatch variation (1000 runs).

spectively. Fig. 4 also shows  $I_1$  has a greater variation than  $I_2$ , because, as seen in corners simulation,  $I_1$  is more dependent on the manufacturing process than  $I_2$ .

It is possible to see in Fig. 5 the behavior of  $I_Q$  versus  $V_{DD}$  ranging from 3 V to 3.6 V. As shown,  $I_Q$  variation for the circuit built with halo-implanted is higher than the uniformly doped circuit. Applying (6), it can be found a sensitivity  $S_{V_{DD}}^{I_Q}$  of  $0.7\%$  for uniformly doped transistors and  $15.3\%$  for halo-implanted transistors. This difference is due to halo-implanted not having a well-defined saturation current, thus making the current reference source circuit more susceptible to supply voltage variations.

Fig. 6 shows the curves of  $I_1$  and  $I_2$  related to the temperature variation, as shown the uniformly doped transistors is less susceptible to temperature variation than the circuit built with halo-implanted transistors. Additionally, the circuit with halo-implanted transistors presents a mismatch between  $I_1$  and  $I_2$  near the  $I_Q$  operating point. The sensitivity of the current reference source related to the temperature is given by (7). The  $TC$  values for the circuits built with uniformly doped and halo-implanted transistors are, respectively,  $23.8 \text{ ppm}/^\circ\text{C}$  and  $66.8 \text{ ppm}/^\circ\text{C}$ .

A ramp signal is apply to analyze the operation of the circuit when it turns on. We perform a transient simulation using a rise time of  $10 \mu\text{s}$ . The startup time is measured when the circuits

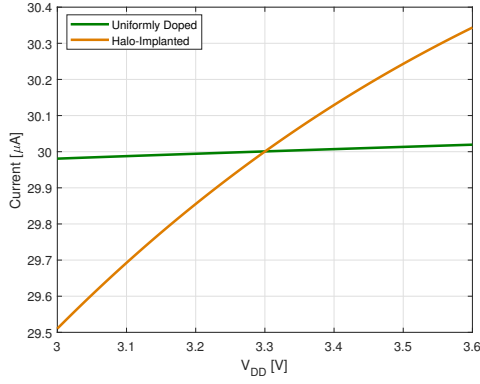


Fig. 5. Variation of  $I_Q \times V_{DD}$  using doped uniformly and halo-implanted transistors.

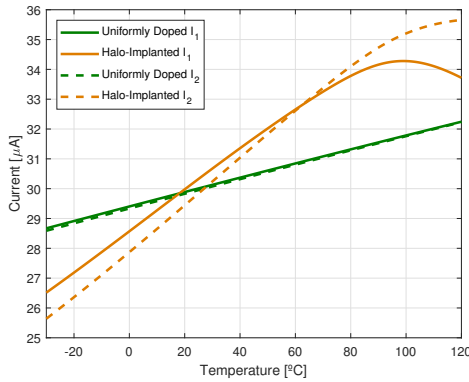
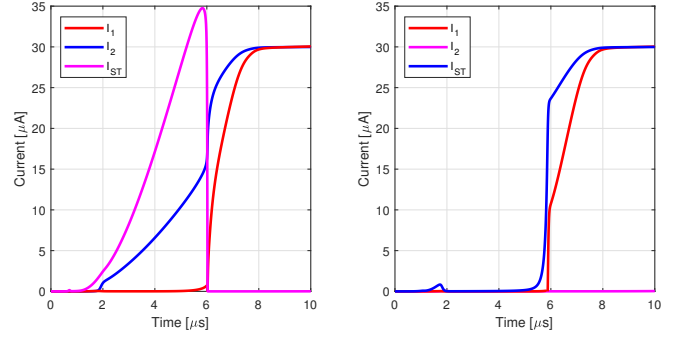


Fig. 6. Variation of  $I_1$  and  $I_2$  related to temperature using uniformly doped and halo-implanted.

starts to turn on to achieve 90% of the current reference value, i.e.,  $27 \mu\text{A}$ . Fig. 7a and 7b show the transient simulations obtained for the start-up circuits. It is possible to see that what differs in both circuits is the maximum current drained by the start-up circuit and the maximum current after achieve the current reference. The maximum current drained by the start-up circuit with the CMOS inverter is  $34.75 \mu\text{A}$ , while the circuit start-up with the MOS capacitor is  $0.04 \mu\text{A}$ . The maximum current after achieve the current reference of  $30 \mu\text{A}$  by the start-up with MOS inverter and with MOS capacitor is, respectively,  $0.01 \mu\text{A}$  and  $0.03 \mu\text{A}$ . The startup time and active area are the same for both circuits,  $6.66 \mu\text{s}$  and  $7969 \mu\text{m}^2$ , respectively. The start-up circuit chosen to initialize the current reference source is the circuit start-up with MOS capacitor for having a low maximum current drained compared to the start-up with MOS inverter.

## V. CONCLUSION

The purpose of this paper was to compare the performance of a current reference source tolerant to supply voltage variations built with uniformly doped and halo-implanted transistors. We designed a topology with a biasing established by it is own current reference, thus implementing a current reference source of  $30 \mu\text{A}$ .



(a) Start-up with CMOS Inverter (b) Start-up with MOS Capacitor  
Fig. 7. Transient Simulation of  $I_1$ ,  $I_2$  and  $I_{ST}$  of start-up circuit.

The results showed that the halo-implanted transistors are not able to maintain the intended biasing and is more susceptible to temperature and supply voltage variations, because it does not have a well-defined saturation current and it presents high mismatch compared to uniformly doped transistors.

Thus, the best choice between these implementations is a current reference source built with uniformly doped transistors with a  $S_{V_{DD}}^{I_Q}$  of 0.7% and a  $TC$  of  $23.8 \text{ ppm}/^\circ\text{C}$ . For the start-up circuit, the best option between the designs presented in this manuscript is the start-up with a MOS transistor operating as a capacitor, which presents the smaller current drain.

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